



# 17th IEEE European Test Symposium

ANNECY, FRANCE - IMPERIAL PALACE  
May 28<sup>th</sup> - June 1<sup>st</sup>, 2012

## Call for Contributions

The IEEE European Test Symposium (ETS) is Europe's premier forum dedicated to presenting and discussing scientific results, emerging ideas, practical applications, hot topics and new trends in the area of electronic-based circuits and system testing. A Test Spring School will be organized in conjunction with ETS'12.

In 2012 ETS will take place in Imperial Palace, Annecy, France and is being organized by TIMA Laboratory (CNRS, Grenoble INP, UJF) and sponsored by the Test Technology Technical Council of the IEEE Computer Society.

ETS'12 is offering commercial vendors the opportunity to give technical presentations in a track parallel to the technical paper sessions. These presentations will be listed in the symposium program along with the technical sessions, and should be targeted to the ETS technical audience. The Vendor Sessions differ from other ETS presentations in that company names, logos, and product names may be mentioned explicitly. Typical content includes product descriptions, case studies, best practices, and user testimonials.

Presentation opportunities of 30-minute duration are available: Proposal selection is based on the technical content and relevance to ETS'12 audience and topics. Attendance at the sessions is open to all symposium attendees, and vendor representatives will be able to hand out literature at the session. Proposals for the Vendor Sessions should be technical or application focused, rather than overtly sales-and-marketing focused. The areas of interest of ETS'12 include (but are not limited to) the following topics:

### TOPICS

You are invited to participate and submit contributions to ETS'12. The areas of interest include (but are not limited to) the following topics.

- Analog Test
- ATE Hardware and Software
- Automatic Test Generation
- Board Test and Diagnosis
- Boundary Scan Test
- Built-In Self Test (BIST)
- Current-Based Test
- Defect-Based Test
- Delay and Performance Test
- Dependability
- Design for Test(ability) - DfT
- Design Verification and Validation
- Diagnosis and Debug
- Economics of Test
- Failure Analysis
- Fault Modeling and Simulation
- Fault Tolerance
- High-Speed I/O Test
- Memory Test and Repair
- MEMS Test
- Microprocessor Test
- Mixed-Signal Test
- Nanotechnology Test
- On-line Test
- Power Issues in Test
- Reliability
- RF Test
- Self-Repair
- Signal Integrity Test
- Stacked IC Test
- Standards in Test
- System Test
- System-in-Package (SiP) Test
- System-on-Chip (SoC) Test
- Soft Errors
- Test(ability) Synthesis
- Test of Reconfigurable Systems
- Test Quality
- Thermal Issues in Test
- Yield Analysis and Enhancement

### VENDOR SESSION SUBMISSIONS

A submission to the ETS'12 Vendor Sessions can be an abstract, extended abstract or full paper (max. six pages); submission of a full paper is preferred, but not required. Proposals should be submitted via the ETS'12 website; detailed submissions instructions can also be found there (go to <http://www.ieee-ets.org>, follow the link to ETS'12, and then select Submission Instructions). Key dates for submissions:

- Submission deadline (for Vendor Sessions only): **January 27th, 2012**
- Notification of acceptance: **February 17, 2012**
- Camera-ready manuscript: **April 2nd, 2012**

### ETS'12 Corporate Support

Every year, ETS is financially supported by several companies. The support money is used to reduce the registration fees and hence make the event more accessible to all its attendees. In return, the corporate supporters are allowed to make publicity in various ways. ETS has defined four different support grades (Bronze, Silver, Gold, and Platinum), each with different support amounts and publicity options.

To find out more, contact Michele Portolan or Régis Leveugle, details below.

### FURTHER INFORMATION

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